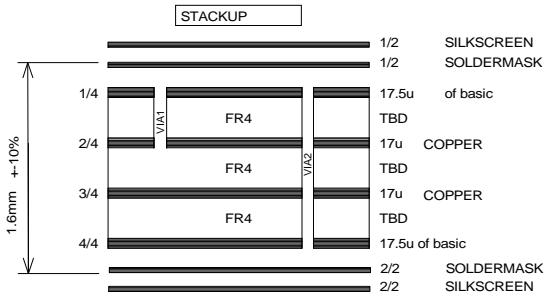
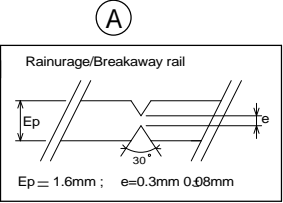



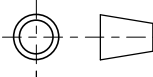
LEGENDE DE PERCEGE / DRILL LEGEND			
ALL UNITS ARE IN MILLIMETERS			
FIGURE	DIAMETRE / HOLESIZE	PLATED	Qty / Qty
+	0,30 mm (PERCE)	PLATED	1264
⊙	1,00 mm +0,10 -0,05	PLATED	678
•	1,10 mm +0,10 -0,05	PLATED	48
⊗	1,40 mm +0,10 -0,05	PLATED	272
◇	3,20 mm +0,15 -0,10	PLATED	20




VIA1 : FLAT PAD VIA LASER TOP
(Filled Copper or resine)
PAD 200um, Drill 100um

BGA 49 ball full 7x7 pitch 500u
LAYER 2 : WIRE ≈150u MINI

ARTWORKS	LAYER N°	PCB	REV.	TYPE
TOP LAYER	1	OM5577	00	311
INT. 1 LAYER	2	OM5577	00	311
INT. 2 LAYER	3	OM5577	00	311
INT. 3 LAYER	-	-	-	311
INT. 4 LAYER	-	-	-	311
INT. 5 LAYER	-	-	-	311
INT. 6 LAYER	-	-	-	311
INT. 7 LAYER	-	-	-	311
INT. 8 LAYER	-	-	-	311
BOTTOM LAYER	4	OM5577	00	311
POWER_1	-	-	-	311
POWER_2	-	-	-	311
POWER_3	-	-	-	311
POWER_4	-	-	-	311
POWER_5	-	-	-	311
SOLDER MASK TOP	5	OM5577	00	312
SOLDER MASK BOT	6	OM5577	00	312
SILKSCREEN TOP	7	OM5577	00	380
SILKSCREEN BOT	8	OM5577	00	380
MILLING	9	OM5577	00	313

Date	Draw by	Verify	Modifications		IND.
Date : 18/02/2015		Material:FR4 TG150 LOW CTEz 16/10 17.5 uM of basic Finition : Ni/Au chemical Protection : SOLDERMASK <div>TOP BOTTOM</div>	Marging : +/-0.1	Nbr of layers : 4	
Draw by : ASCO_SR			Manufact.level : 5	Silkscreen	
Checked by: J.GESLIN			Scale : 1/1	TOP :YES BOTTOM:NO	
Project : PN7120					
NXP Semiconductors 2,Esplanade Anton Philips Campus Effisience Colombelles BP 2000 - 14906 CAEN CEDEX 9			 <div>All rights are reserved. Reproduction in whole or in part is prohibited without the written consent of the copyright owner</div>		
DRILL MANUFACTURING PN7120 NFC Controller Board BeagleBone/Raspberry Pi Interface Board			SIZE A3	OM5577-300	REV. 00 <div>1 / 2</div>

ARTWORKS	LAYER Nb	PCB	REV.	TYPE
TOP LAYER	1	OM5577	00	311
INT. 1 LAYER	2	OM5577	00	311
INT. 2 LAYER	3	OM5577	00	311
INT. 3 LAYER	-	-	-	311
INT. 4 LAYER	-	-	-	311
INT. 5 LAYER	-	-	-	311
INT. 6 LAYER	-	-	-	311
INT. 7 LAYER	-	-	-	311
INT. 8 LAYER	-	-	-	311
BOTTOM LAYER	4	OM5577	00	311
POWER_1	-	-	-	311
POWER_2	-	-	-	311
POWER_3	-	-	-	311
POWER_4	-	-	-	311
POWER_5	-	-	-	311
SOLDER MASK TOP	5	OM5577	00	312
SOLDER MASK BOT	6	OM5577	00	312
SILKSCREEN TOP	7	OM5577	00	380
SILKSCREEN BOT	8	-	-	380
MILLING	9	OM5577	00	313

Date	Draw by	Verify	Modifications	IND.
Date : 18/02/2015		Material:FR4 TG150 LOW CTEz 16/10 17.5 uM of basic		Nbr of layers : 4
Draw by : ASCO_SR		Finition : Ni/Au chemical		Silkscreen
Checked by: J.GESLIN		Protection : SOLDERMASK TOP BOTTOM		TOP :YES BOTTOM:NO
Project : PN7120		Scale : 1/1		
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DRILL MANUFACTURING PN7120 NFC Controller Board BeagleBone/Raspberry Pi Interface Board			SIZE A3	REV. 00
			OM5577-300	PL. 2/2